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IAP12 Rec'd PCT/PTO 16 JUN 2006

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)	Andrew Holland	Examiner:	Unassigned
Serial No.:	Unassigned	Group Art Unit:	Unassigned
Confirmation No.:	Unassigned	Docket:	1662-2 PCT/US
Filed:	Herewith	Dated:	June 16, 2006
For:	SEMICONDUCTOR PACKAGE WITH INTEGRATED HEATSINK AND ELECTROMAGNETIC SHIELD		

Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

I hereby certify this correspondence is being deposited with the United States Postal Service as Express Mail EV803489531US, postpaid in an envelope, addressed to: Mail Stop PCT, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on June 16, 2006.

Signed: _____

Judith Post
Judith Post

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the duty to disclose under 37 C.F.R. §1.56, attached hereto is PTO Form-1449 listing the references which may be considered material in evaluating the patentability of the claims of the above-identified application.

These references have been cited in one or more search reports from a foreign patent office in corresponding International Application No. PCT/GB2004/005217, filed on December 17, 2004. Copies of the International Search Report, the British Search Report and foreign references cited therein are enclosed for the convenience of the Examiner.

Some of these references are in English and thus no concise explanation of their relevance is required. The relevancy statement for other references not in English are provided herebelow. In addition, pursuant to the PTO's waiver under 37 C.F.R. §1.98(a)(2)(i), no copies of the cited U.S. references are being provided herewith. (1276 OG 55).

JP 06-350012 A has been cited in the International Search Report under Category X with regards to the international claims 1-11 and 13-40 indicated to be relevant. The reference discloses a data link, a manufacturing method thereof, and machining device for reducing the number of parts and simplifying the manufacturing steps. No full translation of this reference is available to Applicant at this time. However, an English language abstract is attached.

JP 07-288332 A has been cited in the corresponding International Search Report under Category X with regards to the international claims 1-11 and 13-40 indicated to be relevant. The reference discloses a light element assembly and the suppression of its noise and ensurement of its shield by covering the surface of the IC chip with an opaque resin, and by covering the whole periphery of the light element assembly shield thereafter with a transparent resin. No full translation of this reference is available to the Applicant at this time. However, an English language abstract is attached.

JP 05-166988 has been cited in the International Search Report under Category X with regards to the international claims 1-5, 7, 9, 20-34, and 38-40 being indicated to be relevant. The reference discloses a semi-conductor device small in size and large in heat dissipating capacity by a method wherein the outer section of the heat dissipation fins protruding from the side face of a resin-sealed package are bent and arranged so as to overlap each other in a top view. No full of this reference is available to the Applicant at this time. However, an English language abstract is attached.

DE 199 15 065 A1 has been cited in the International Search Report under Category A with regards to the international claim 18 being indicated to be relevant. The reference discloses a semiconductor module with heat dissipation feature which has a power component and control

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component chip on the fastening face of the carrier. No full translation of this reference is available to the Applicant at this time. However, an English language abstract is attached.

As this Information Disclosure Statement is being filed before the issuance of a first Office Action, no fee is deemed necessary. If, however, a fee is necessary, the Commissioner is hereby authorized to charge such fee to Deposit Account No. 08-2461.

If the Examiner has any questions or comments relating to the present application, he or she is respectfully invited to contact Applicants' attorney at the telephone number set forth below.

Respectfully submitted,



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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE (Rev. 2-32) PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 1662-2 PCT/US	SERIAL NO. 10/1583525 Unassigned
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		APPLICANT Andrew Holland	CONFIRMATION NO. Unassigned
(Use several sheets if necessary)		FILING DATE Unassigned	GROUP Unassigned

U.S. PATENT PUBLICATIONS

EXAMINE R INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
		2003/0081392 A1	05/01/2003	Cady et al.			
		2003/0193794 A1	10/16/2003	Reis et al.			

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
		5,057,903	10/15/1991	Olla			
		5,536,906	07/16/1996	Haas, Jr. et al			
		6,165,817	12/26/2000	Akram et al.			
		6,376,907 B1	04/23/2002	Takano et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION	
							YES	NO
		05-166988	07/02/1993	Japan				X
		06-350012	12/22/1994	Japan				X
		07-288332	10/31/1995	Japan				X
		DE 199 15 065 A1	02/10/2000	Dutch				X
		EP 1 049 192 A2	11/02/2000	EPO				X

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.